



(1.27 mm) .050"

CLP-107-02-F-D-P

CLP-115-02-L-D

CLP-130-02-L-D

CLP-116-02-F-DH

CLP SERIES

LOW PROFILE DUAL WIPE SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?CLP

Insulator Material:

Black Liquid Crystal Polymer

Contact Material:

Phosphor Bronze

Plating:

Sn or Au over

50 μ" (1.27 μm) Ni

Current Rating (CLP/FTSH):

3.3 A per pin

(1 pin powered per row)

Voltage Rating:

240 VAC/340 VDC

Operating Temp Range:

-55 °C to +125 °C

Contact Resistance:

10 mΩ

Insertion Depth:

Top Entry = (1.40 mm) .055"

minimum, Bottom Entry =

(2.41 mm) .095" minimum

plus board thickness

DH Entry = (2.31 mm) .091"

to (2.67 mm) .105"

Normal Force:

60 grams (0.59 N) average

Max Cycles:

100 with 10 μ" (0.25 μm) Au

RoHS Compliant:

Yes

Mates with:

FTSH, FTS, FW

APPLICATIONS

CLP FTSH

HORIZONTAL

PASS-THRU

High-reliability
Tiger Claw™
contacts

(1.27 mm x 1.27 mm)
.050" x .050"
micro pitch

Low profile
(2.21 mm)
.087"

Surface
mount

Suitable for pass-through
applications



PROCESSING

Lead-Free Solderable:

Yes

SMT Lead Coplanarity:

(0.10 mm) .004" max (02-35)

(0.15 mm) .006" max (36-50)

RECOGNITIONS

For complete scope of
recognitions see
www.samtec.com/quality



ALSO AVAILABLE (MOQ Required)

- Single row
 - Other platings
- Contact Samtec.

Note: Some sizes, styles and options are non-standard, non-returnable.

